

## 3A, 50V - 1000V High Efficient Surface Mount Rectifier

#### **FEATURES**

- AEC-Q101 qualified
- Glass passivated chip junction
- Ideal for automated placement
- Low forward voltage drop
- Low profile package
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

#### **APPLICATIONS**

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

#### **MECHANICAL DATA**

- Case: DO-214AB (SMC)
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.210g (approximately)

KEY PARAMETERS				
PARAMETER	VALUE	UNIT		
I <sub>F</sub>	3	А		
V <sub>RRM</sub>	50 - 1000	V		
I <sub>FSM</sub>	150	А		
T <sub>J MAX</sub>	150	°C		
Package	DO-214AB (SMC)			
Configuration	Single die			





DO-214AB (SMC)



ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25°C unless otherwise noted)										
PARAMETER	SYMBOL	HS 3AH	HS 3BH	HS 3DH	HS 3FH	HS 3GH	HS 3JH	HS 3KH	HS 3MH	UNIT
Marking code on the device		HS3A	HS3B	HS3D	HS3F	HS3G	HS3J	HS3K	HS3M	
Repetitive peak reverse voltage	V <sub>RRM</sub>	50	100	200	300	400	600	800	1000	V
Reverse voltage, total rms value	V <sub>R(RMS)</sub>	35	70	140	210	280	420	560	700	V
Forward current	I <sub>F</sub>	F 3			Α					
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	I <sub>FSM</sub>	I <sub>FSM</sub> 150				A				
Junction temperature	TJ	T <sub>J</sub> - 55 to +150			°C					
Storage temperature	T <sub>STG</sub>	- 55 to +150			°C					



THERMAL PERFORMANCE					
PARAMETER	SYMBOL	ТҮР	UNIT		
Junction-to-ambient thermal resistance	R <sub>eja</sub>	60	°C/W		

ELECTRICAL SPECIFICATIONS (T <sub>A</sub> = 25°C unless otherwise noted)						
PARAMETER		CONDITIONS	SYMBOL	ТҮР	MAX	UNIT
(1)	HS3AH HS3BH HS3DH HS3FH			-	1.0	V
Forward voltage <sup>(1)</sup>	HS3GH	I <sub>F</sub> = 3A, T <sub>J</sub> = 25°C	V <sub>F</sub>	-	1.3	V
	HS3JH HS3KH HS3MH			-	1.7	V
				-	10	μA
Reverse current @ rated $V_R^{(2)}$		T <sub>J</sub> = 125°C	I <sub>R</sub>	-	250	μA
Junction capacitance	ction capacitance HS3AH HS3BH HS3DH HS3FH HS3GH 1MHz, V <sub>R</sub> = 4.0V	CJ	80	-	pF	
	HS3JH HS3KH HS3MH			50	-	pF
Reverse recovery time HS3AH HS3BH HS3DH HS3FH HS3GH HS3JH HS3KH	I <sub>F</sub> = 0.5A, I <sub>R</sub> = 1.0A, I <sub>rr</sub> = 0.25A	t <sub>rr</sub>	-	50	ns	
	HS3JH			-	75	ns

#### Notes:

1. Pulse test with PW = 0.3ms

2. Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE <sup>(1)</sup>	PACKAGE	PACKING		
HS3xH	DO-214AB (SMC)	3,000 / Tape & Reel		

#### Notes:

1. "x" defines voltage from 50V(HS3AH) to 1000V(HS3MH)



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

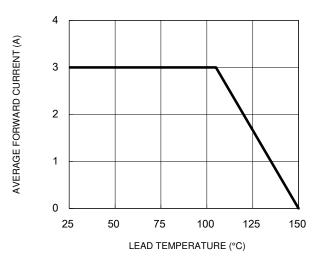
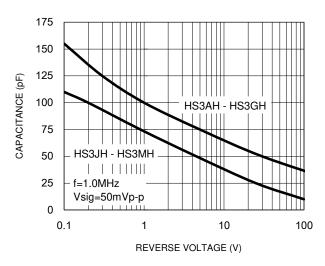
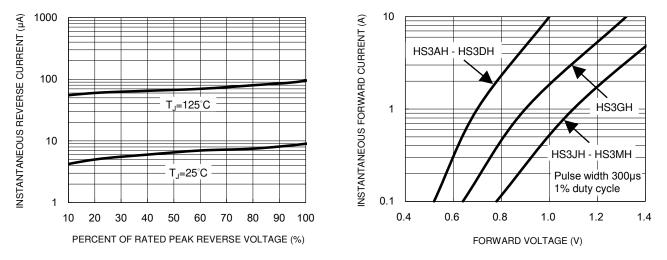


Fig.1 Forward Current Derating Curve

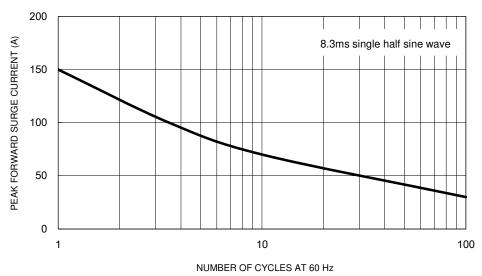
#### **Fig.3 Typical Reverse Characteristics**



**Fig.4 Typical Forward Characteristics** 



#### Fig.5 Maximum Non-Repetitive Forward Surge Current

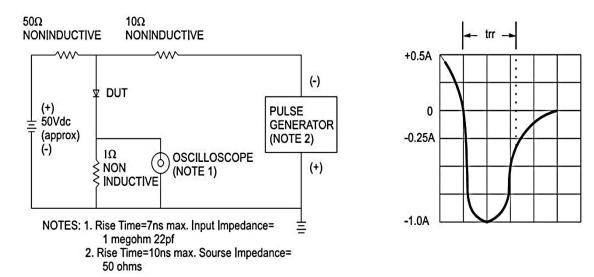


#### Fig.2 Typical Junction Capacitance



#### **CHARACTERISTICS CURVES**

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$ 

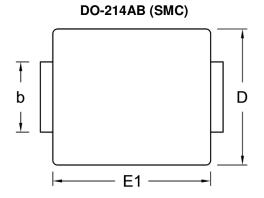


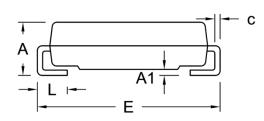
#### Fig.6 Reverse Recovery Time Characteristic and Test Circuit Diagram

# HS3AH – HS3MH Taiwan Semiconductor



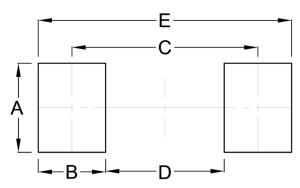
## PACKAGE OUTLINE DIMENSIONS





DIM. Unit (m		(mm)	nm) Unit (inch)		
	Min.	Max.	Min.	Max.	
A	2.00	2.62	0.079	0.103	
A1	0.10	0.20	0.004	0.008	
b	2.90	3.20	0.114	0.126	
с	0.15	0.31	0.006	0.012	
D	5.59	6.22	0.220	0.245	
E	7.75	8.13	0.305	0.320	
E1	6.60	7.11	0.260	0.280	
L	1.00	1.60	0.039	0.063	

## SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
A	3.30	0.130
В	2.50	0.098
С	6.90	0.272
D	4.40	0.173
E	9.40	0.370

## **MARKING DIAGRAM**



- P/N = Marking Code
- G = Green Compound
- YW = Date Code
- F = Factory Code



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